

5/22/03  
#16 Amended



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Divisional Application of:

Akihiro SASAKI et al.

Serial No. 10/012,462

Filed: December 12, 2001

For: PHOTSENSITIVE RESIN  
COMPOSITION, PATTERNING  
METHOD, AND ELECTRONIC  
COMPONENTS

)  
) Atty. Docket No.: TSUK 0004  
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) Group Art Unit: 1756  
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)  
) Examiner: CHACKO-DAVIS, Daborah  
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)  
) Date: May 19, 2003  
)

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AMENDMENT (A)

**BOX: FEE AMENDMENT**

Assistant Commissioner for Patents  
Washington, D. C. 20231

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Sir:

In response to the official Office Action, dated December 19, 2002, please amend the above captioned application as follows:

IN THE CLAIMS:

✓  
Please cancel claim 5 without prejudice.

Kindly amend claims 1, 4 and 6, and add new claims 10-12 as follows.

1. (Amended) A photosensitive resin composition comprising an aromatic polyimide precursor, wherein a 10  $\mu$ m thick layer of the aromatic polyimide precursor has a light transmittance at a wavelength of 365 nm of at least 1%, and a 10  $\mu$ m thick polyimide film made from the resin composition by imidation ring closure and deposited on a silicon substrate has light transmittance at a wavelength of 365 nm of at least 1% and a residual stress of at most 25 MPa,

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